SN74AHCT1G86 单路 2 输入异或门

1 特性

- 工作电压范围为 4.5 V 至 5.5V
- 电压为 5V 时，t_{pd} 最大值为 8ns
- 低功耗，I_{CC} 最大值为 10A
- 电压为 5V 时，输出驱动为 8mA
- 输入兼容 TTL 电压
- 闩锁性能超过 250mA，符合 JESD 17 规范的要求

2 应用

- 工业 PC
- 步进电机
- 交流逆变器驱动器
- 笔记本电脑
- 智能仪表: 数据集中器
- 企业级服务器

3 说明

SN74AHCT1G86 是一款单路 2 输入异或门。该器件采用正逻辑执行布尔函数
$Y = A \oplus B$ or $Y = \overline{A}B + A\overline{B}$。

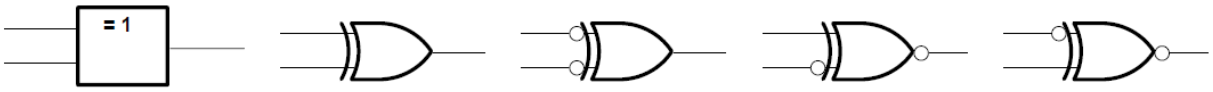
器件信息(1)

器件型号	封装	封装尺寸（标称值）
SN74AHCT1G86	DBV（SOT-23，5）	2.90mm × 1.60mm
	DCK（SC-70，5）	2.00mm × 1.25mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

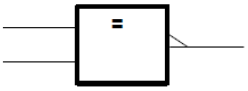
An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.

EXCLUSIVE OR



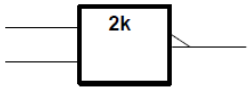
These five equivalent exclusive-OR symbols are valid for an SN74AHCT1G86 gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



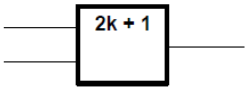
The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

异或逻辑

Table of Contents

4 Revision History

Changes from Revision M (February 2015) to Revision N (August 2022) **Page**

- 更新了整个文档中的表格、图和交叉参考的编号格式.....1

Changes from Revision L (January 2003) to Revision M (February 2015) **Page**

- 添加了 *引脚配置和功能* 部分、*ESD 等级* 表、*特性说明* 部分、*器件功能模式*、*应用和实现* 部分、*电源相关建议* 部分、*布局* 部分、*器件和文档支持* 部分以及 *机械、封装和可订购信息* 部分.....1

5 Pin Configuration and Functions

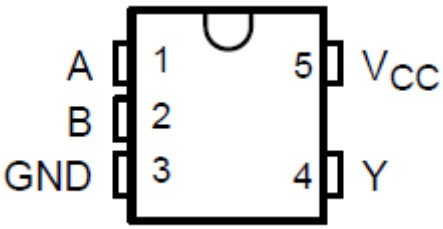


图 5-1. DBV or DCK Package 5-Pin SOT-23 Top View

PIN		TYPE(1)	DESCRIPTION
NO.	NAME		
1	A	I	A input
2	B	I	B input
3	GND	–	Ground pin
4	Y	O	Output
5	Vcc	–	Power pin

(1) Signal Types: I = Input, O = Output, I/O = Input or Output

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		–0.5	7	V
V_I	Input voltage(2)		–0.5	7	V
V_O	Output voltage(2)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0		–20	mA
I_{OK}	Output clamp current	V_O < 0 or V_O > V_{CC}	–20	20	mA
I_O	Continuous output current	V_O = 0 to V_{CC}	–25	25	mA
	Continuous current through V_{CC} or GND		–50	50	mA
T_{stg}	Storage temperature		–65	150	°C
T_J	Junction Temperature			150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5		5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		5.5	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			–8	mA
I_{OL}	Low-level output current			8	mA
t/v	Input transition rise or fall rate			20	ns/V
T_A	Operating free-air temperature	–40		125	°C

6.4 Thermal Information

THERMAL METRIC[1]		SN74AHCT1G86		UNIT
		DBV (SOT-23)	DCK (SC-70)	
		5 PINS	5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	208.2	287.6	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	76.1	97.7	
$R_{\theta JB}$	Junction-to-board thermal resistance	52.5	65	
ψ_{JT}	Junction-to-top characterization parameter	4	2	
ψ_{JB}	Junction-to-board characterization parameter	51.8	64.2	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			–40°C to 85°C		–40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	High level output voltage	I_{OH} = –50 µA	4.5 V	4.4	4.5		4.4		4.4		V
		I_{OH} = –8 mA		3.94			3.8		3.8		
V_{OL}	Low level output voltage	I_{OL} = 50 µA	4.5 V			0.1		0.1		0.1	V
		I_{OL} = 8 mA				0.36		0.44		0.44	
I_I	Input leakage current	V_I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1		±1	µA
I_{CC}	Supply current	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			1		10		10	µA
ΔI_{CC} [1]	Supply-current change	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			1.35		1.5		1.5	mA
C_i	Input capacitance	$V_I = V_{CC}$ or GND	5 V		2	10		10		10	pF

(1) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

6.6 Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C		– 40°C to 85°C		– 40°C to 125°C		UNIT
				TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	C_L = 15 pF	5	6.2	1	8	1	9	ns
t_{PHL}				5	6.2	1	8	1	9	
t_{PLH}	A or B	Y	C_L = 50 pF	5.5	7.9	1	9	1	10	ns
t_{PHL}				5.5	7.9	1	9	1	10	

6.7 Operating Characteristics

V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	No load,	f = 1 MHz	18	pF

6.8 Typical Characteristics

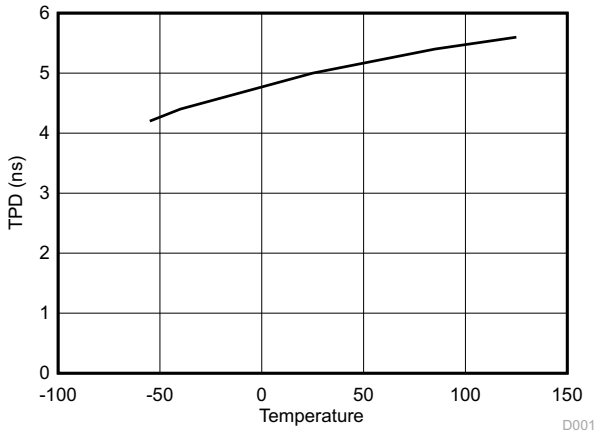
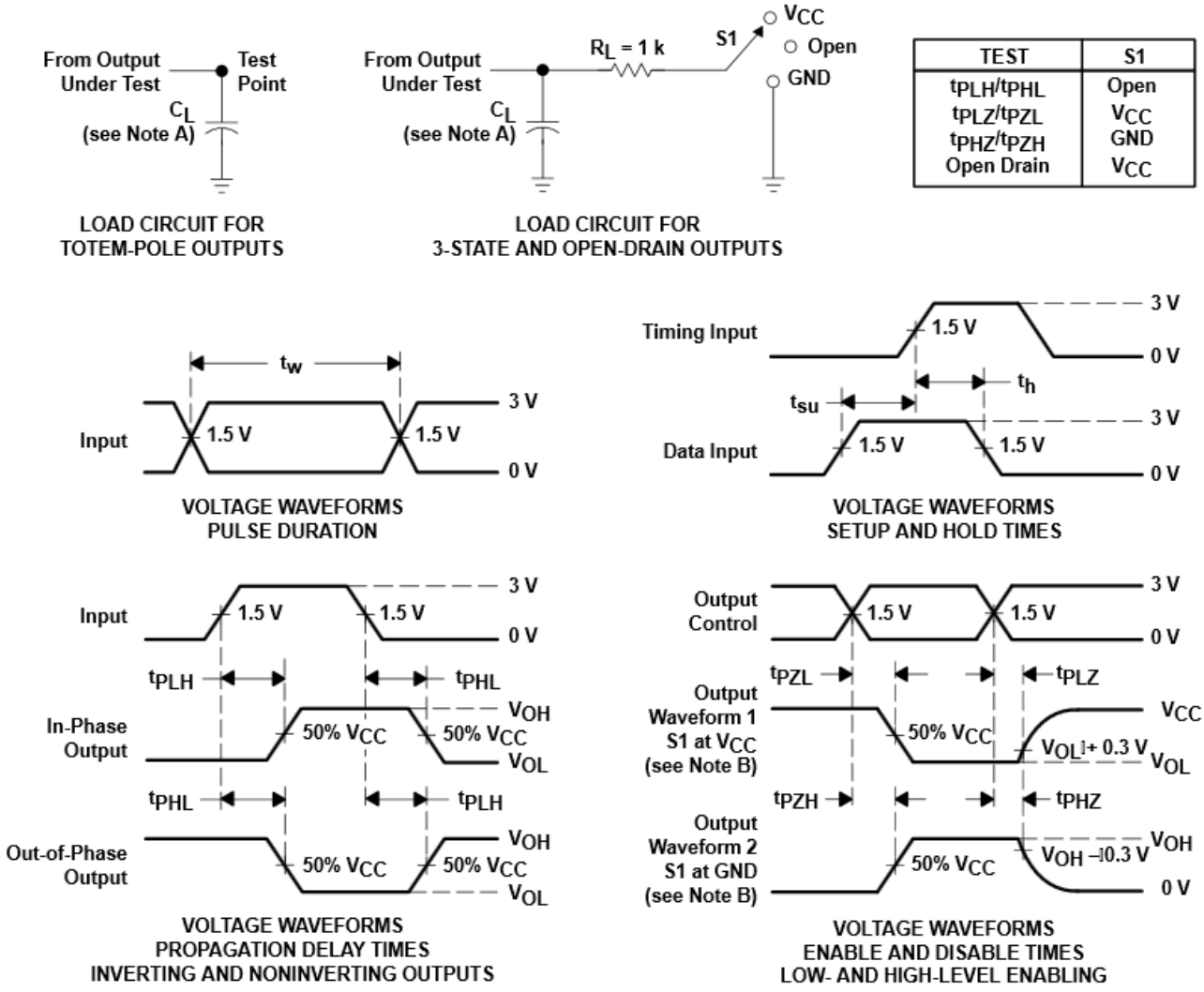


图 6-1. TPD vs. Temperature

7 Parameter Measurement Information

7.1



NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR 1 MHz, Z_O = 50 , t_r 3 ns, t_f 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.
E. All parameters and waveforms are not applicable to all devices.

图 7-1. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

The SN74AHCT1G86 is a single 2-input exclusive-OR gate. The device performs the Boolean function $Y = A \oplus B$ or $Y = \overline{A}B + A\overline{B}$ in positive logic.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

8.2 Functional Block Diagram

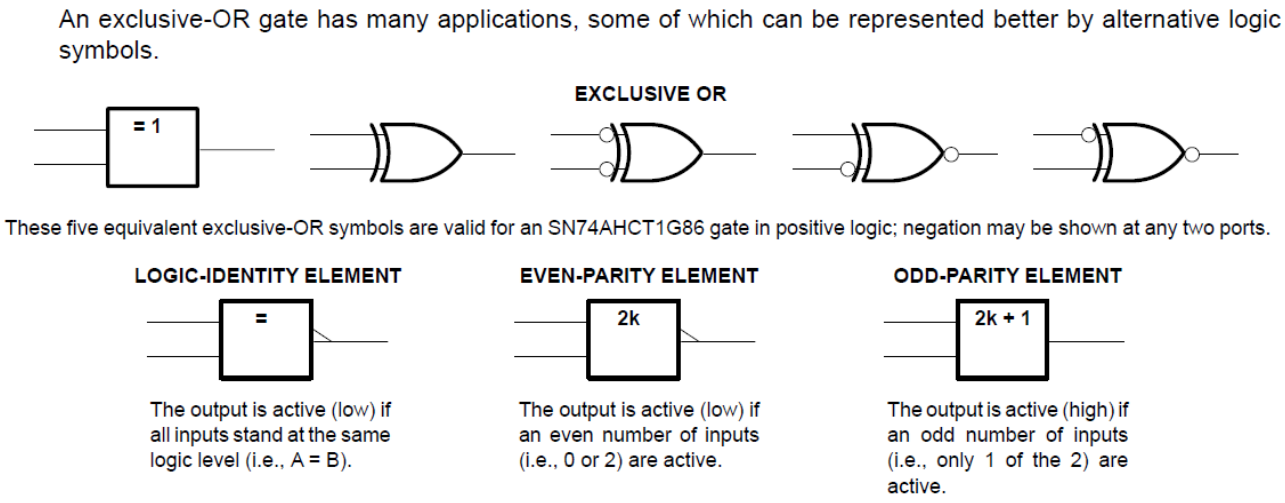


图 8-1. Exclusive-OR Logic

8.3 Feature Description

The device is ideal for operating in a 5-V logic system. The low propagation delay allows fast switching and higher speeds of operation. In addition, the low power consumption makes this device a good choice for portable and battery power-sensitive applications.

8.4 Device Functional Modes

表 8-1. Function Table

INPUTS(1)		OUTPUT(2)
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

(1) H = High Voltage Level, L = Low Voltage Level, X = Don’t Care
(2) H = Driving High, L = Driving Low, Z = High Impedance State

9 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客 户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

9.1 Application Information

The SN74AHCT1G86 is a Low drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The input switching levels have been lowered to accommodate TTL inputs of 0.8-V V_{IL} and 2-V V_{IH}. This feature makes it Ideal for translating up from 3.3 V to 5 V.

9.2 Typical Application

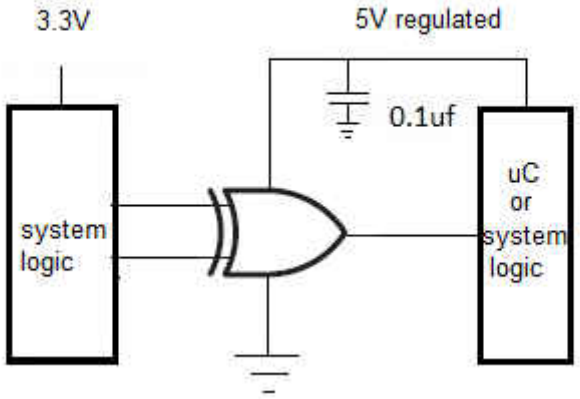


图 9-1. Typical Application Schematic

9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so consider routing and load conditions to prevent ringing.

9.2.2 Detailed Design Procedure

- Recommended input conditions:
  - Rise time and fall time specs. See ($\Delta t/\Delta V$) in *节 6.3*.
  - Specified high and low levels. See (V_{IH} and V_{IL}) in *节 6.3*.
- Recommended output conditions:
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.
  - Outputs should not be pulled above V_{CC}.

9.2.3 Application Curves

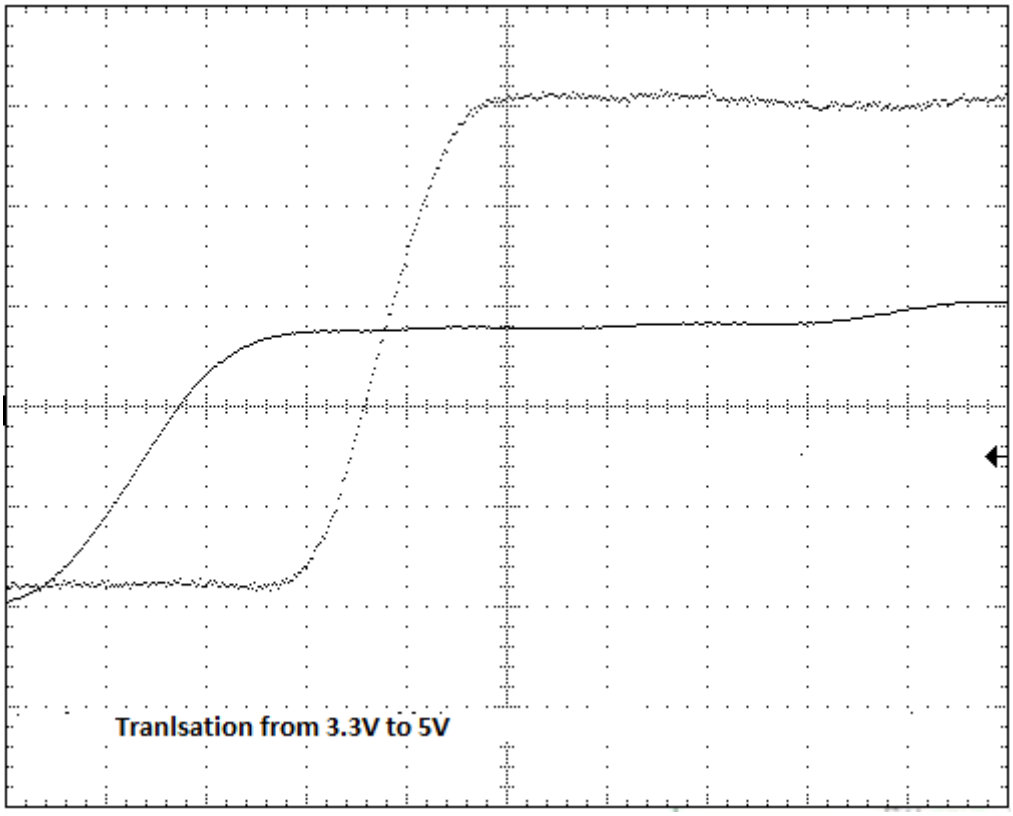


图 9-2. Translation From 3.3 V to 5.5 V

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the 节 6.3.

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1-μF capacitor and if there are multiple Vcc terminals then TI recommends a 0.01-μF or 0.022-μF capacitor for each power terminal. Multiple bypass capacitors can be paralleled to reject different frequencies of noise. Frequencies of 0.1 μF and 1 μF are commonly used in parallel. The bypass capacitor should be installed as close as possible to the power terminal for best results.

11 Layout

11.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only three of the four buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} whichever make more sense or is more convenient. Floating outputs is generally acceptable, unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the I.O’s so they also cannot float when disabled.

11.2 Layout Example

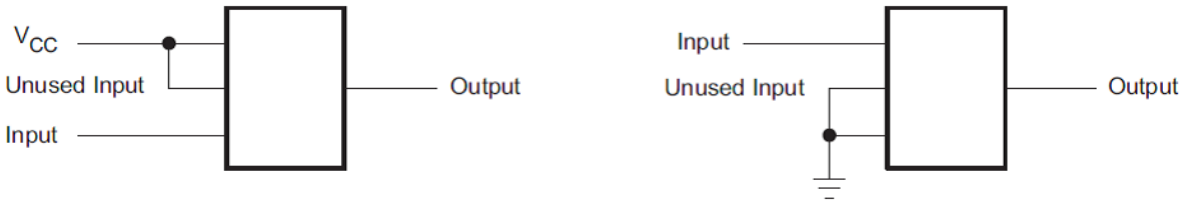


图 11-1. Layout Recommendation

12 Device and Documentation Support

12.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 *订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

12.2 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

12.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

12.4 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.5 术语表

TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74AHCT1G86DBVRG4	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B86G	Samples
74AHCT1G86DBVTG4	ACTIVE	SOT-23	DBV	5	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B86G	Samples
SN74AHCT1G86DBVR	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	(B863, B86G, B86J, B86S)	Samples
SN74AHCT1G86DBVT	ACTIVE	SOT-23	DBV	5	250	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	(B863, B86G, B86J, B86S)	Samples
SN74AHCT1G86DCKR	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	(BH3, BHG, BHJ, BHL, BHS)	Samples
SN74AHCT1G86DCKT	ACTIVE	SC70	DCK	5	250	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	(BH3, BHG, BHJ, BHL, BHS)	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN74AHCT1G86 :

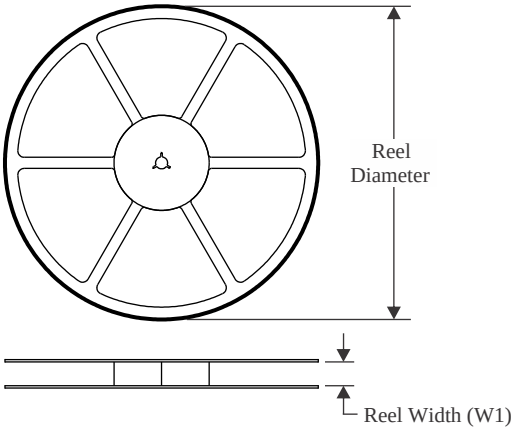
- Automotive : SN74AHCT1G86-Q1

NOTE: Qualified Version Definitions:

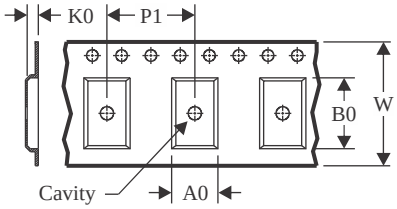
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

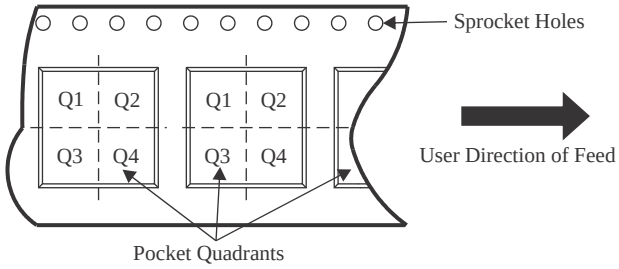


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

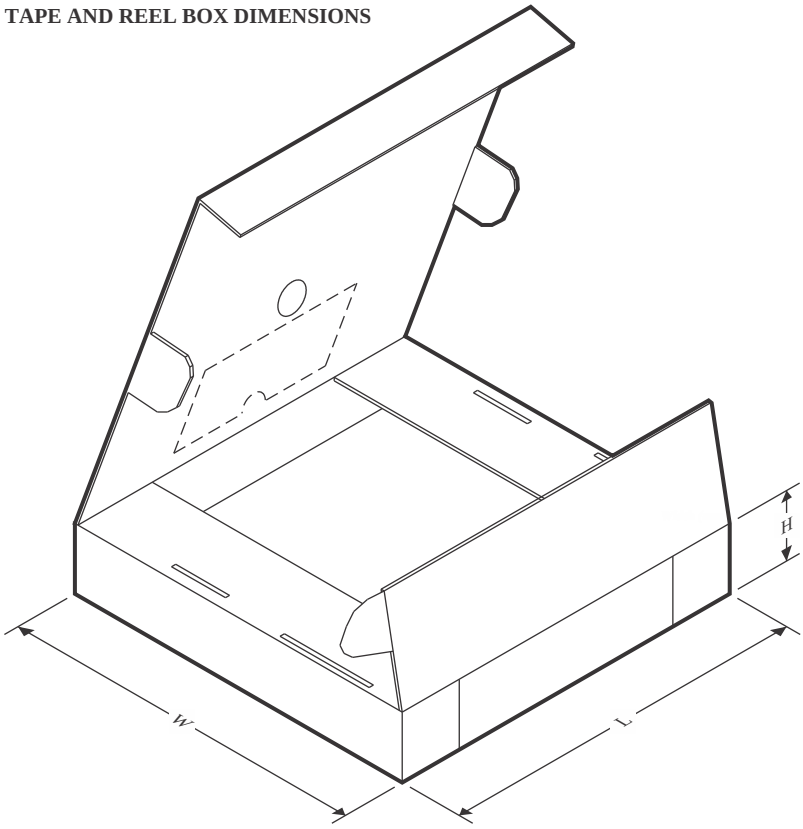
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AHCT1G86DBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
74AHCT1G86DBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHCT1G86DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
SN74AHCT1G86DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHCT1G86DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHCT1G86DBVR	SOT-23	DBV	5	3000	178.0	9.2	3.3	3.23	1.55	4.0	8.0	Q3
SN74AHCT1G86DBVT	SOT-23	DBV	5	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHCT1G86DBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
SN74AHCT1G86DBVT	SOT-23	DBV	5	250	178.0	9.2	3.3	3.23	1.55	4.0	8.0	Q3
SN74AHCT1G86DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHCT1G86DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AHCT1G86DCKR	SC70	DCK	5	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74AHCT1G86DCKR	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
SN74AHCT1G86DCKT	SC70	DCK	5	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AHCT1G86DCKT	SC70	DCK	5	250	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3

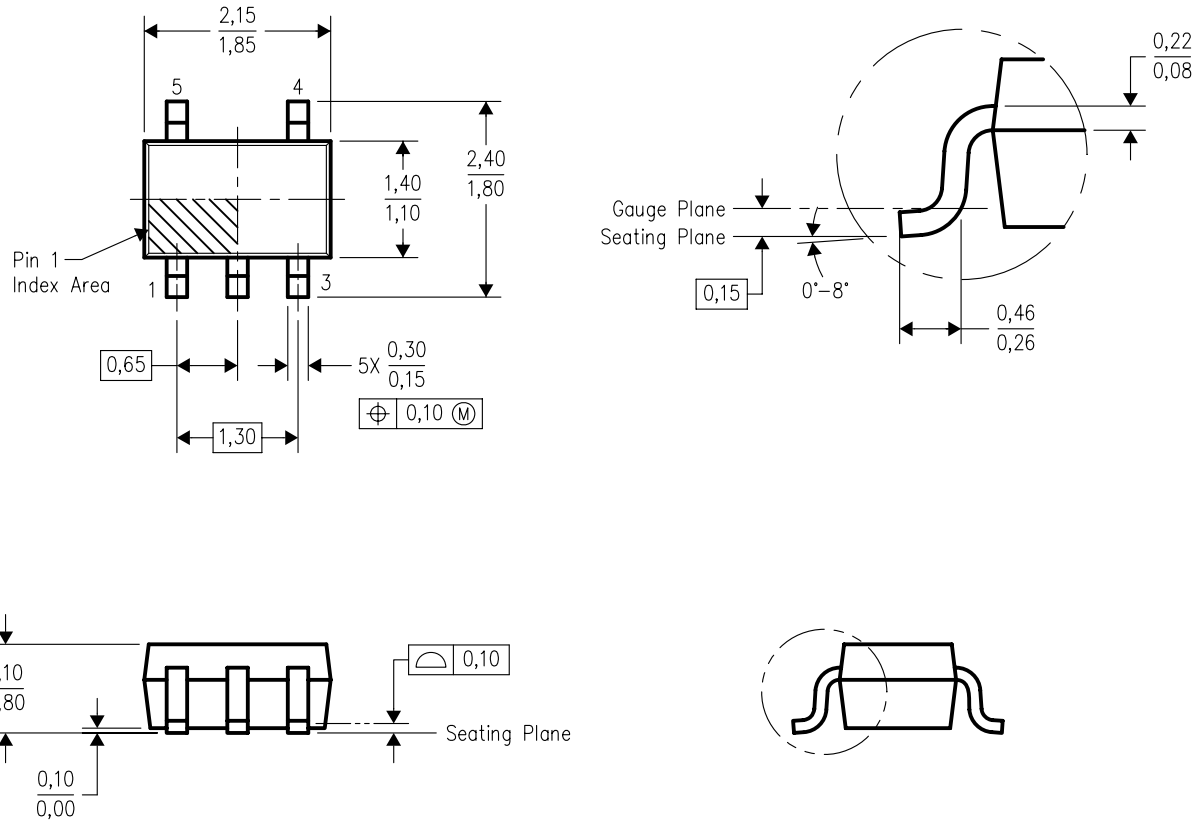
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AHCT1G86DBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
74AHCT1G86DBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74AHCT1G86DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74AHCT1G86DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74AHCT1G86DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
SN74AHCT1G86DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74AHCT1G86DBVT	SOT-23	DBV	5	250	202.0	201.0	28.0
SN74AHCT1G86DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74AHCT1G86DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74AHCT1G86DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74AHCT1G86DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74AHCT1G86DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74AHCT1G86DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
SN74AHCT1G86DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74AHCT1G86DCKT	SC70	DCK	5	250	180.0	180.0	18.0

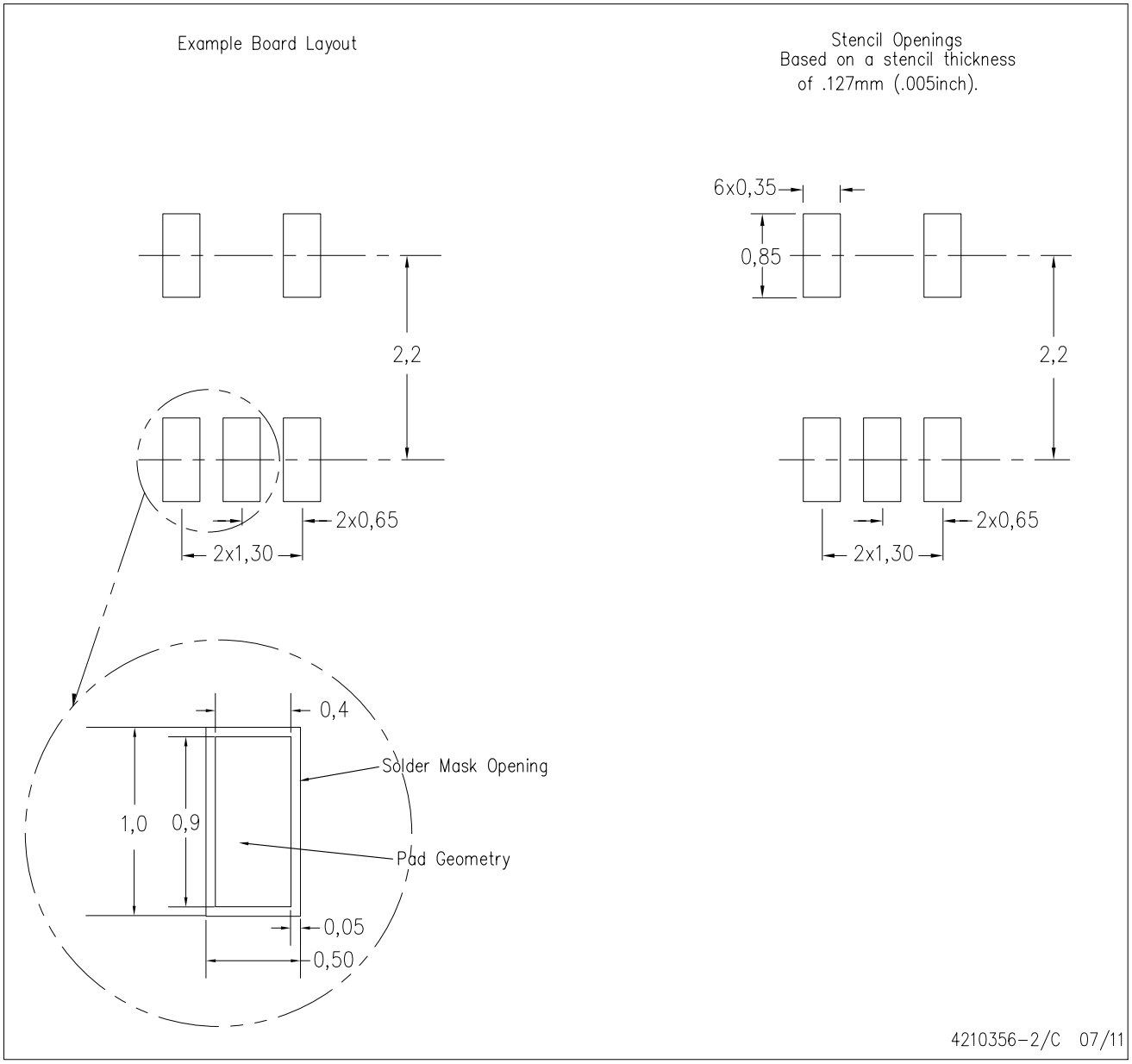
DCK (R–PDSO–G5) PLASTIC SMALL–OUTLINE PACKAGE



4093553–3/G 01/2007

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO–203 variation AA.

DCK (R–PDSO–G5) PLASTIC SMALL OUTLINE



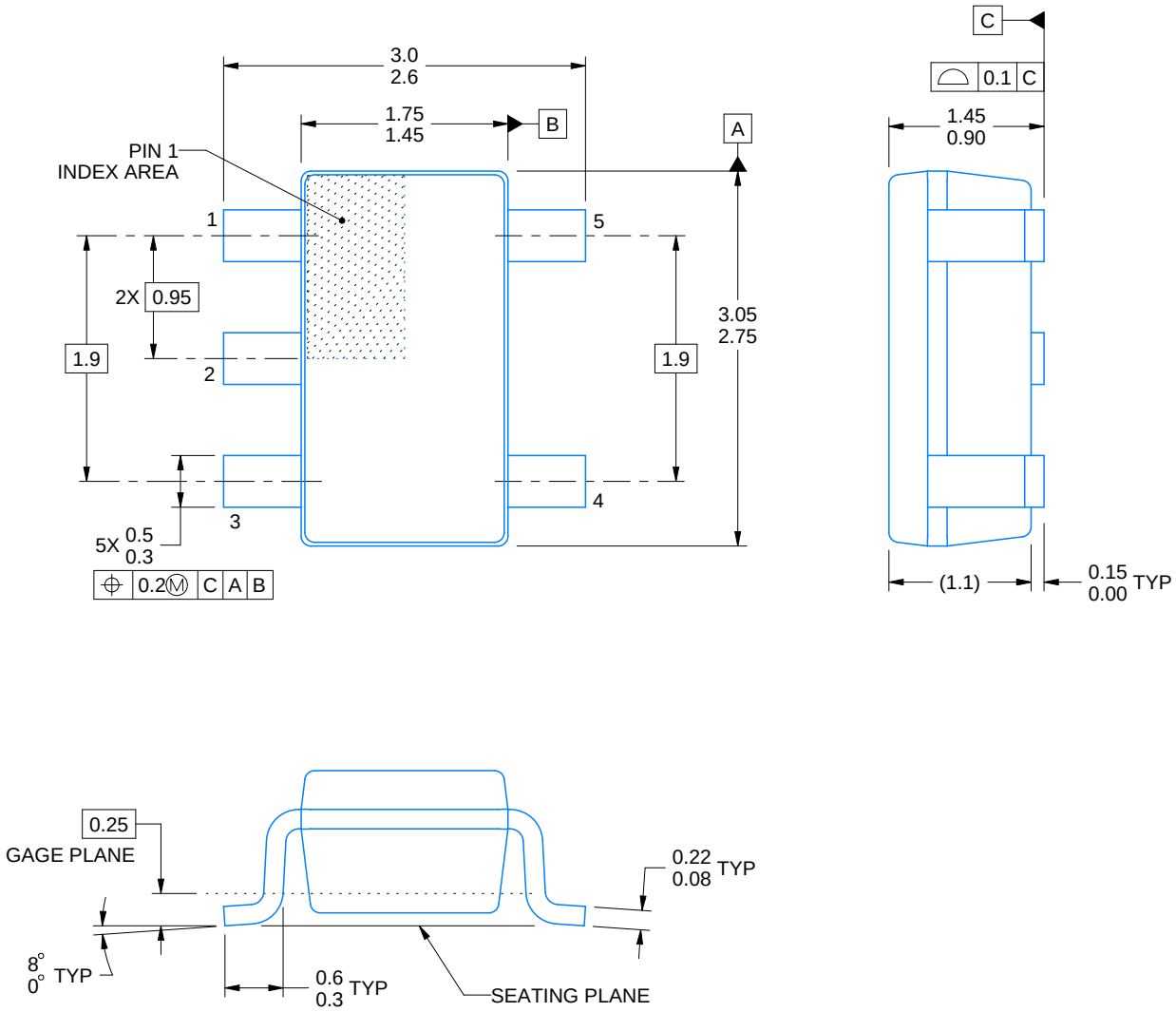
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. Publication IPC–7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC–7525 for other stencil recommendations.

PACKAGE OUTLINE

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



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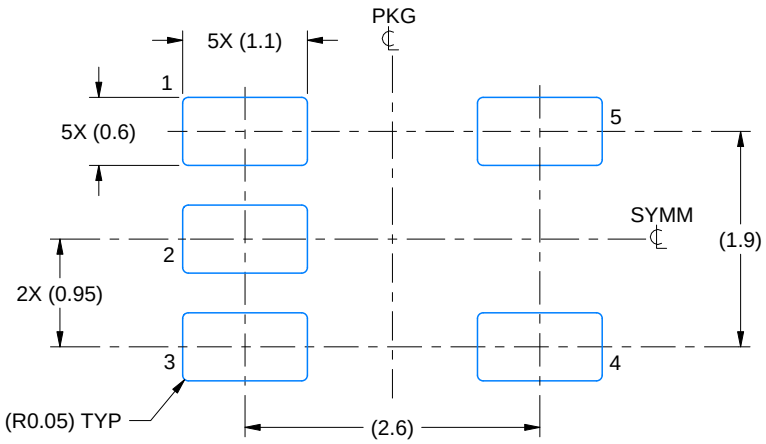
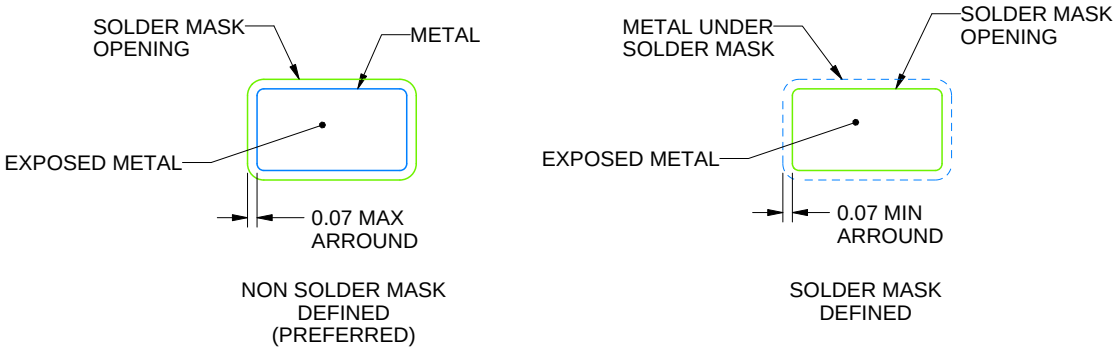
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

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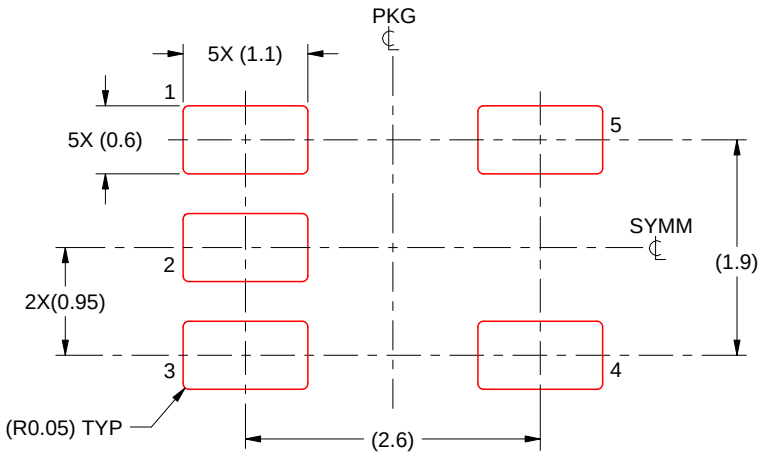
NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

重要声明和免责声明

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